

ABSTRACT

A package for holding a temperature sensitive optical device. The package includes a substrate, and a first link connecting to the optical device at a first attachment point, and connecting to the substrate at a location remote from the first attachment point. The package also includes a second link connecting to the optical device at a second attachment point that is remote from the first attachment point, the second link connecting to the substrate at a location remote from the second attachment point. The substrate, the first and the second links imposing a strain variation to the optical device in dependence of temperature.